

# SV-20 Field-Upgradable Brick™

2011 Product Portfolio - Rugged Servers & Workstations



Tactical Systems : A Division of Technology Advancement Group®, Inc.

:: Field-Upgradable CPU™

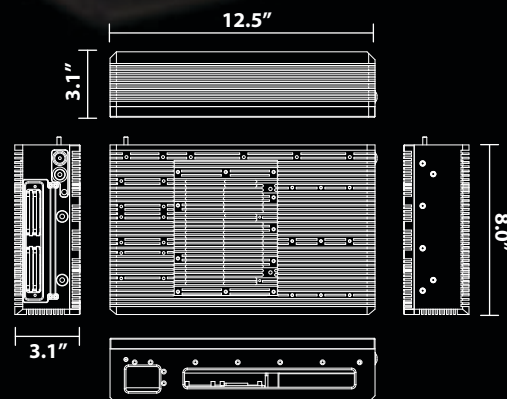
:: Ultra-Mobile Brick™ Computer

:: Latest COM-Express Technology



## Module Options

| Processor Type                 | Chipset                      | Front-Side Bus |
|--------------------------------|------------------------------|----------------|
| Intel® Core™ i7 SV, 2.53GHz    | Intel® Mobile QM57           | 1066 MHz       |
| Intel® Core™ i7 LV, 2.0GHz     | Intel® Mobile QM57           | 1066 MHz       |
| Intel® Core™ i7 ULV, 1.06GHz   | Intel® Mobile QM57           | 800 MHz        |
| Intel® Core™ i5 SV, 2.4GHz     | Intel® Mobile QM57           | 1066 MHz       |
| Intel® Core™ i3 SV, 2.13 GHz   | Intel® 5 Series, Intel® HM55 | 1066 MHz       |
| Intel® Core™2 Duo SV, 2.53 GHz | Intel® GS45, Intel® ICH9EM   | 1066 MHz       |
| Intel® Core™2 Duo SV, 2.26 GHz | Intel® GS45, Intel® ICH9M    | 1066 MHz       |
| Intel® Core™2 Duo LV, 1.86 GHz | Intel® GS45, Intel® ICH9M    | 800 MHz        |
| Intel® Core™2 Duo ULV, 1.2 GHz | Intel® GS45, Intel® ICH9M    | 667 MHz        |
| Intel® Atom™ N270, 1.6 GHz     | Intel® 945GME, 82801GHM      | 533 MHz        |



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## Hardware Specifications

Specifications below are subject to change, contact us for more information.



| Build Characteristics   |  |
|-------------------------|--|
| Product Code            | SV-20 Field-Upgradable Brick™  |
| Product Class           | Servers & Workstations   |
| Chassis Type            | Conduction Cooled Aluminum Alloy (6061-T6)                                     |
| Dimensions              | 8.0" W x 3.1"H x 12.5"D  |
| Weight                  | 11.8 lbs   |
| Mounting Options        | Horizontal and Vertical Mounting Options Available                             |
| Module Characteristics  |  |
| CPU Module Options      | Intel® Core™ i7, i5, & i3 Processors   |
|                         | Intel® Core™2 Duo Processors   |
|                         | Intel® Atom™ Processors  |
| Chipset                 | Intel® Series Chipset  |
| Front Side Bus          | Up-to 1066 MHz   |
| Cache                   | Up-to 6MB Cache  |
| Memory                  | Up-To 8GB (DDR3/DDR2)  |
| Audio Engine            | Digital High Definition Audio Interface with Support for Multiple Audio Codecs |
| Video Engine            | Integrated Intel® Graphics Controller  |
|                         | Dual Display Support (VGA & DVI)   |
|                         | OpenGL 2.1 and DirectX10 Support   |
|                         | Decoding Support MPEG-2   WMV9   H.264   Blue-Ray                              |
| Internal I/O Support    | Up-to 8x USB 2.0   |
| PCI Express Support     | Dual Mini PC Express Internal Slots  |
| Security                | TPM (On Select COMExpress Modules)   |
| System Diagnostics      | Built-In Port 80 Readout   |
| I/O Characteristics     |  |
| 10/100/1000 Ethernet    | 2x RJ-45 Ports   |
| Serial Port             | 1x Serial Port DB9   |
| USB 2.0 Port            | 4x USB 2.0 Ports   |
| Video Port              | 1x DVI-I Port  |
| Audio Port              | Line In, Line Out  |
| External Button Boards  | Primary On/Off, System On/Off, Reset   |
| Storage Characteristics |  |
| Storage Type            | Up-to (4) Removable 1.8" SATA Solid State Drives (SSD)                         |
| Storage Capacity        | 80GB Each SSD (Contact Sales Rep for Larger Storage Options)                   |

| Power Characteristics            |   |
|----------------------------------|---|
| Power Supply Input               | 28VDC - Nom (18-36 VDC Range)   |
| Power Supply Output              | 16VDC   |
| Power Supply EMI Filter          | Compliance for MIL-STD-704 & MIL-STD-1275                                       |
| Power Consumption                | 40W Typical   |
| Software Options                 |   |
| Supported Platforms              | Microsoft®   Linux®   |
| Contact Sales Rep for Options    |   |
| Environmental Characteristics    |   |
| High Temperature Operational     | Designed to Meet MIL-STD 810G Method 501.5, Procedure II (60°C)                 |
| Low Temperature Operational      | Designed to Meet MIL-STD 810G Method 502.5, Procedure II (0°C)                  |
| High Temperature Non-Operational | Designed to Meet MIL-STD 810G Method 501.5, Procedure I (70°C)                  |
| Low Temperature Non-Operational  | Designed to Meet MIL-STD 810G Method 502.5, Procedure I (-20°C)                 |
| Humidity                         | Designed to Meet MIL-STD 810G Method 507.5, Procedure II (0-95% Non-Condensing) |
| Shock                            | Designed to Meet MIL-STD 810G Method 516.6 Procedure I                          |
| Vibration                        | Designed to Meet MIL-STD 810G Method 514.6 Procedure I                          |
| Fungus                           | Designed to Meet MIL-STD 810G Method 508.6                                      |
| Salt/Fog                         | Designed to Meet MIL-STD 810G Method 509.5                                      |
| Warranty & Tech Support          |   |
| Warranty                         | (1) Year Parts and Labor Guarantee (Contact Sales Rep for Extended Warranty)    |
| Tech Support                     | 24x7 Technical Support Provided By TAG (1-877-824-8324   supportstaff@tag.com)  |

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